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<ul> <li>Low Differential Gain and Phase (D<sub>G</sub> = 0.64%, D<sub>P</sub> = 0.1 Degrees Typ)</li> </ul>	D, DBQ, OR PW PACKAGE (TOP VIEW)
<ul> <li>Wide Bandwidth (BW = 300 MHz Min)</li> </ul>	
<ul> <li>Low Crosstalk (X<sub>TALK</sub> = -63 dB Typ)</li> </ul>	IN [] 1 16 [] V <sub>CC</sub> S1 <sub>A</sub> [] 2 15 [] EN
Low Power Consumption	S2 <sub>A</sub> [] 3 14 [] S1 <sub>D</sub>
(I <sub>CC</sub> = 3 μA Max)	D <sub>A</sub> [] 4 13 [] S2 <sub>D</sub>
Bidirectional Data Flow, With Near-Zero	$S1_B$ $\begin{bmatrix} 5 \\ 12 \end{bmatrix}$ $D_D$
Propagation Delay	$S2_B \begin{bmatrix} 6 & 11 \end{bmatrix} S1_C$
<ul> <li>Low ON-State Resistance (r<sub>on</sub> = 3 Ω Typ)</li> </ul>	D <sub>B</sub> [] 7   10 [] S2 <sub>C</sub> GND [] 8   9 [] D <sub>C</sub>
<ul> <li>V<sub>CC</sub> Operating Range From 4.5 V to 5.5 V</li> </ul>	
<ul> <li>I<sub>off</sub> Supports Partial-Power-Down Mode Operation</li> </ul>	RGY PACKAGE
<ul> <li>Data and Control Inputs Provide Undershoot Clamp Diode</li> </ul>	(TOP VIEW) >
<ul> <li>Control Inputs Can Be Driven by TTL or 5-V/3.3-V CMOS Outputs</li> </ul>	1 16
<ul> <li>Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II</li> </ul>	$\begin{array}{c c} S1_A & 2\\ S2_A & 3\\ \end{array} \begin{array}{c} 15 & \overline{EN} \\ 14 & S2_D\\ \end{array}$
<ul> <li>ESD Performance Tested Per JESD 22</li> </ul>	$D_A 4$ 13 $S2_D$
– 2000-V Human-Body Model	S1 <sub>B</sub> 5         12         D <sub>D</sub> S2 <sub>B</sub> 6         11         S1 <sub>C</sub>
(A114-B, Class II)	$D_{\rm B}$ 7 $\Box$ $D_{\rm B}$ 10 $S2_{\rm C}$
<ul> <li>1000-V Charged-Device Model (C101)</li> </ul>	8 9
• Suitable for Both RGB and	BC
Composite-Video Switching	C

## description/ordering information

The TI TS5V330 video switch is a 4-bit 1-of-2 multiplexer/demultiplexer with a single switch-enable ( $\overline{EN}$ ) input. When  $\overline{EN}$  is low, the switch is enabled and the D port is connected to the S port. When  $\overline{EN}$  is high, the switch is disabled and the high-impedance state exists between the D and S ports. The select (IN) input controls the data path of the multiplexer/demultiplexer.

TA	PACKAGE <sup>†</sup>		ORDERABLE PART NUMBER	TOP-SIDE MARKING
	QFN – RGY	Tape and reel	TS5V330RGYR	TE330
	SOIC – D	Tube	TS5V330D	TO51/000
		Tape and reel	TS5V330DR	TS5V330
–40°C to 85°C	SSOP (QSOP) – DBQ	Tape and reel	TS5V330DBQR	TE330
	TSSOP – PW	Tube	TS5V330PW	TE330
	13306 - 610	Tape and reel	TS5V330PWR	1230

#### **ORDERING INFORMATION**

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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## description/ordering information (continued)

Low differential gain and phase make this switch ideal for composite and RGB video applications. This device has wide bandwidth and low crosstalk, making it suitable for high-frequency applications as well.

This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  feature ensures that damaging current will not backflow through the device when it is powered down. This switch maintains isolation during power off.

To ensure the high-impedance state during power up or power down,  $\overline{EN}$  should be tied to V<sub>CC</sub> through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

FUNCTION TABLE							
INP	UTS	INPUT/OUTPUT	FUNCTION				
EN	IN	D	FUNCTION				
L	L	S1	D port = S1 port				
L	Н	S2	D port = S2 port				
Н	Х	Z	Disconnect				

#### **PIN DESCRIPTIONS**

PIN NAME	DESCRIPTION	
S1, S2	Analog video I/Os	
D	Analog video I/Os	
IN	Select input	
EN	Switch-enable input	



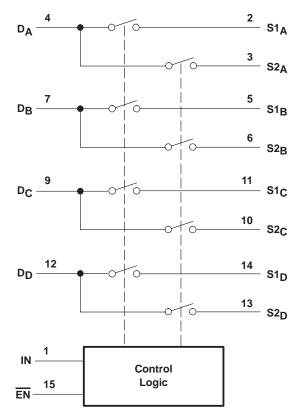
# TS5V330 **QUAD SPDT WIDE-BANDWIDTH VIDEO SWITCH** WITH LOW ON-STATE RESISTANCE SCDS164A – MAY 2004 – REVISED MAY 2004

	PARAMETER DEFINITIONS
PARAMETER	DESCRIPTION
ron	Resistance between the D and S ports, with the switch in the ON state
I <sub>OZ</sub>	Output leakage current measured at the D and S ports, with the switch in the OFF state
los	Short-circuit current measured at the I/O pins
V <sub>IN</sub>	Voltage at the IN pin
VEN	Voltage at the EN pin
C <sub>IN</sub>	Capacitance at the control (EN, IN) inputs
COFF	Capacitance at the analog I/O port when the switch is OFF
CON	Capacitance at the analog I/O port when the switch is ON
VIH	Minimum input voltage for logic high for the control (EN, IN) inputs
VIL	Minimum input voltage for logic low for the control (EN, IN) inputs
V <sub>hys</sub>	Hysteresis voltage at the control (EN, IN) inputs
VIK	I/O and control (EN, IN) inputs diode clamp voltage
VI	Voltage applied to the D or S pins when D or S is the switch input
VO	Voltage applied to the D or S pins when D or S is the switch output
ΙΗ	Input high leakage current of the control (EN, IN) inputs
Ι <sub>Ι</sub>	Input low leakage current of the control (EN, IN) inputs
Ц	Current into the D or S pins when D or S is the switch input
IO	Current into the D or S pins when D or S is the switch output
loff	Output leakage current measured at the D or S ports, with $V_{CC} = 0$
tON	Propagation delay measured between 50% of the digital input to 90% of the analog output when switch is turned ON
<sup>t</sup> OFF	Propagation delay measured between 50% of the digital input to 90% of the analog output when switch is turned OFF
BW	Frequency response of the switch in the ON state measured at -3 dB
X <sub>TALK</sub>	Unwanted signal coupled from channel to channel. Measured in $-dB$ . $X_{TALK} = 20 \log V_O/V_I$ . This is a nonadjacent crosstalk.
O <sub>IRR</sub>	Off isolation is the resistance (measured in –dB) between the input and output with the switch OFF.
DG	Magnitude variation between analog input and output pins when the switch is ON and the dc offset of composite-video signal varies at the analog input pin. In the NTSC standard, the frequency of the video signal is 3.58 MHz, and dc offset is from 0 to 0.714 V.
DP	Phase variation between analog input and output pins when the switch is ON and the dc offset of composite-video signal varies at the analog input pin. In the NTSC standard, the frequency of the video signal is 3.58 MHz, and dc offset is from 0 to 0.714 V.
ICC	Static power-supply current
ICCD	Variation of I <sub>CC</sub> for a change in frequency in the control (EN, IN) inputs
ΔICC	This is the increase in supply current for each control input that is at the specified voltage level, rather than V <sub>CC</sub> or GND.



# **TS5V330** QUAD SPDT WIDE-BANDWIDTH VIDEO SWITCH WITH LOW ON-STATE RESISTANCE SCDS164A – MAY 2004 – REVISED MAY 2004

# functional diagram (positive logic)





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### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, V <sub>CC</sub>
Control input voltage range, V <sub>IN</sub> (see Notes 1 and 2) –0.5 V to 7 V
Switch I/O voltage range, V <sub>I/O</sub> (see Notes 1, 2, and 3) –0.5 V to 7 V
Control input clamp current, I <sub>IK</sub> (V <sub>IN</sub> < 0)
I/O port clamp current, $I_{I/OK}$ ( $V_{I/O}$ < 0)
ON-state switch current, II/O (see Note 4) ±128 mA
Continuous current through V <sub>CC</sub> or GND terminals
Package thermal impedance, θ <sub>JA</sub> (see Note 5): D package
(see Note 5): DBQ package
(see Note 5): PW package
(see Note 6): RGY package
Storage temperature range, T <sub>stg</sub> –65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltages are with respect to ground, unless otherwise specified.

- 2. The input and output voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
- 3. VI and VO are used to denote specific conditions for VI/O.
- 4. II and IO are used to denote specific conditions for II/O.
- 5. The package thermal impedance is calculated in accordance with JESD 51-7.
- 6. The package thermal impedance is calculated in accordance with JESD 51-5.

## recommended operating conditions (see Note 7)

		MIN	MAX	UNIT
VCC	Supply voltage	4	5.5	V
VIH	High-level control input voltage (EN, IN)	2	5.5	V
VIL	Low-level control input voltage (EN, IN)	0	0.8	V
VANALOG	Analog I/O voltage	0	2	V
T <sub>A</sub>	Operating free-air temperature	-40	85	°C

NOTE 7: All unused control inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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# electrical characteristics over recommended operating free-air temperature range, V<sub>CC</sub> = 5 V $\pm$ 10% (unless otherwise noted)

PARA	METER		TEST CONDI	TIONS		MIN	TYP†	MAX	UNIT
VIK	EN, IN	V <sub>CC</sub> = 4.5 V,	I <sub>IN</sub> = -18 mA					-1.8	V
V <sub>hys</sub>	EN, IN						150		mV
IIН	EN, IN	V <sub>CC</sub> = 5.5 V,	$V_{IN}$ and $V_{EN} = V_{CC}$					±1	μA
۱ <sub>IL</sub>	EN, IN	V <sub>CC</sub> = 5.5 V,	$V_{IN}$ and $V_{EN}$ = GND					±1	μA
Ioz‡		V <sub>CC</sub> = 5.5 V,	$V_{O} = 0$ to 5.5 V, $V_{I} = 0$ ,	Switch OFF				±1	μΑ
IOS§		V <sub>CC</sub> = 5.5 V,	$V_{O} = 0.5 V_{CC},$ $V_{I} = 0,$	Switch ON		50			mA
loff		V <sub>CC</sub> = 0,	$V_{O} = 0$ to 5.5 V,	$V_{I} = 0$				1	μA
ICC		V <sub>CC</sub> = 5.5 V,	$I_{I/O} = 0,$	Switch ON or O	FF			3	μA
∆ICC	EN, IN	V <sub>CC</sub> = 5.5 V,	One input at 3.4 V,	Other inputs at V	√ <sub>CC</sub> or GND			2.5	mA
ICCD		V <sub>CC</sub> = 5.5 V, V <sub>EN</sub> = GND,	D and S ports open,	VIN input switch	ing 50% duty cycle			0.25	mA/ MHz
CIN	EN, IN	$V_{IN}$ or $V_{EN} = 0$ ,	f = 1 MHz				3.5		pF
0	D port	N/- 0	f = 1 MHz,				6		- 5
COFF	S port	$V_{I} = 0,$	Outputs open	Switch OFF			4		pF
C <sub>ON</sub>		$V_{I} = 0,$	f = 1 MHz, Outputs open	Switch ON			14		pF
- ¶			V <sub>I</sub> = 1 V,	I <sub>O</sub> = 13 mA,	RL = 75 Ω		3	7	0
ron¶		$V_{CC} = 4.5 \text{ V}$ $V_I = 2 \text{ V}$ , $I_O = 26 \text{ mA}$ , F		RL = 75 Ω		7	10	Ω	

VI, VO, II, and IO refer to I/O pins.

<sup>†</sup> All typical values are at V<sub>CC</sub> = 5 V (unless otherwise noted),  $T_A = 25^{\circ}C$ .

<sup>‡</sup> For I/O ports, I<sub>OZ</sub> includes the input leakage current.

§ The IOS test is applicable to only one ON channel at a time. The duration of this test is less than one second.

I Measured by the voltage drop between the D and S terminals at the indicated current through the switch. ON-state resistance is determined by the lower of the voltages of the two (D or S) terminals.

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V ±10%, $R_L$ = 75 $\Omega$ , $C_L$ = 20 pF (unless otherwise noted) (see Figure 5)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	MIN	ТҮР	МАХ	UNIT
tON	S	D		2.5	6	ns
<sup>t</sup> OFF	S	D		1.1	6	ns

# dynamic characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm 10\%$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP†	MAX	UNIT
D <sub>G</sub> #	R <sub>L</sub> = 150 Ω,	f = 3.58 MHz, see Figure 6			0.64		%
DP <sup>#</sup>	RL = 150 Ω,	f = 3.58 MHz, see Figure 6			0.1		Deg
BW	$R_L = 150 \Omega$ , see Fig	jure 7		300			MHz
XTALK	RL = 150 Ω,	f = 10 MHz,	$R_{IN}$ = 10 $\Omega$ , see Figure 8		-63		dB
O <sub>IRR</sub>	RL = 150 Ω,	f = 10 MHz, see Figure 9			-60		dB

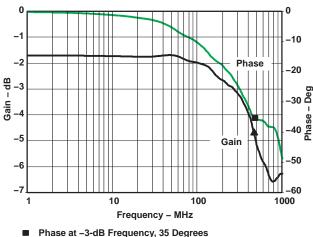
<sup>†</sup> All typical values are at  $V_{CC}$  = 5 V (unless otherwise noted),  $T_A$  = 25°C.

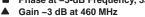
<sup>#</sup>D<sub>G</sub> and D<sub>P</sub> are expressed in absolute magnitude.

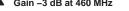


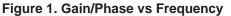
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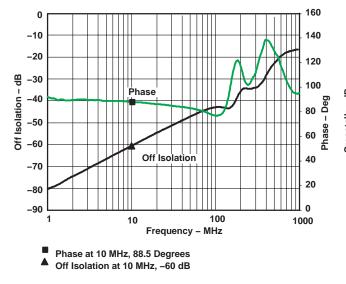
# **OPERATING CHARACTERISTICS**



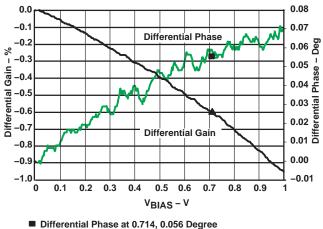












▲ Differential Gain at 0.714, -0.63%

Figure 2. Differential Gain/Phase vs VBIAS

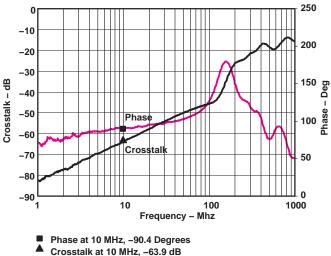
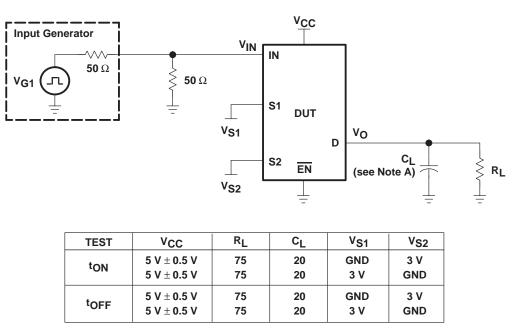


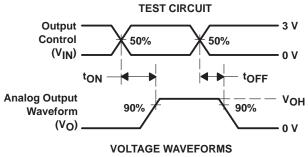
Figure 4. Crosstalk vs Frequency



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## PARAMETER MEASUREMENT INFORMATION





tON AND TOFF TIMES

NOTES: A. CL includes probe and jig capacitance.

B. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z<sub>O</sub> = 50  $\Omega$ , t<sub>f</sub>  $\leq$  2.5 ns, t<sub>f</sub>  $\leq$  2.5 ns.

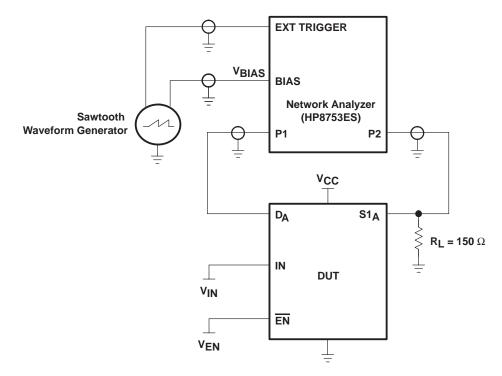
C. The outputs are measured one at a time, with one transition per measurement.

Figure 5. Test Circuit and Voltage Waveforms



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## PARAMETER MEASUREMENT INFORMATION



NOTE A: For additional information on measurement method, refer to the TI application report, Measuring Differential Gain and Phase, literature number SLOA040.

## Figure 6. Test Circuit for Differential Gain/Phase Measurement

Differential gain and phase are measured at the output of the ON channel. For example, when  $V_{IN} = 0$ ,  $V_{EN} = 0$ , and  $D_A$  is the input, the output is measured at  $S1_A$ .

## HP8753ES setup

Average = 20 RBW = 300 Hz ST = 1.381 s P1 = -7 dBMCW frequency = 3.58 MHz

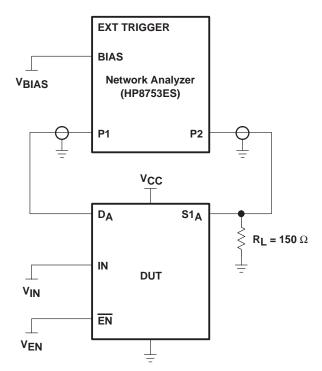
#### sawtooth waveform generator setup

 $V_{BIAS} = 0$  to 1 V Frequency = 0.905 Hz



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## PARAMETER MEASUREMENT INFORMATION



## Figure 7. Test Circuit for Frequency Response (BW)

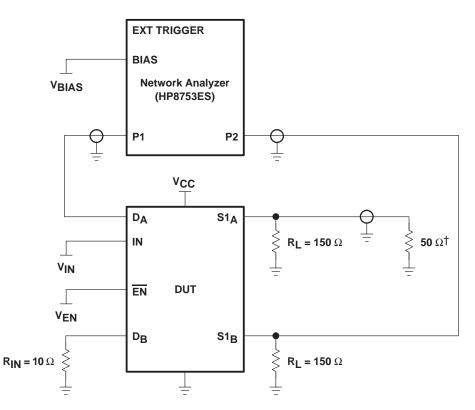
Frequency response is measured at the output of the ON channel. For example, when  $V_{IN} = 0$ ,  $V_{EN} = 0$ , and  $D_A$  is the input, the output is measured at  $S1_A$ . All unused analog I/O ports are left open.

## HP8753ES setup

Average = 4RBW = 3 kHz $V_{BIAS} = 0.35 V$ ST = 2 s P1 = 0 dBM



## PARAMETER MEASUREMENT INFORMATION



 $^{\dagger}$  A 50- $\!\Omega$  termination resistor is needed for the network analyzer.

## Figure 8. Test Circuit for Crosstalk (XTALK)

Crosstalk is measured at the output of the nonadjacent ON channel. For example, when  $V_{IN} = 0$ ,  $V_{EN} = 0$ , and  $D_A$  is the input, the output is measured at S1<sub>B</sub>. All unused analog input (D) ports and output (S) ports are connected to GND through 10- $\Omega$  and 50- $\Omega$  pulldown resistors, respectively.

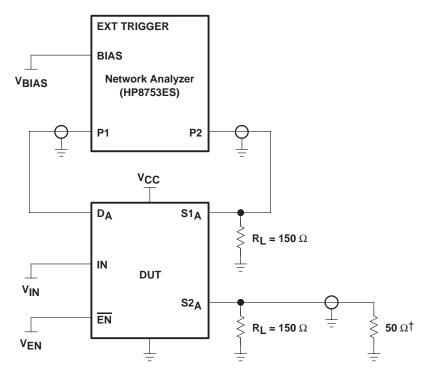
#### HP8753ES setup

Average = 4 RBW = 3 kHz  $V_{BIAS} = 0.35 V$ ST = 2 s P1 = 0 dBM



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## PARAMETER MEASUREMENT INFORMATION



<sup>†</sup> A 50- $\Omega$  termination resistor is needed for the network analyzer.

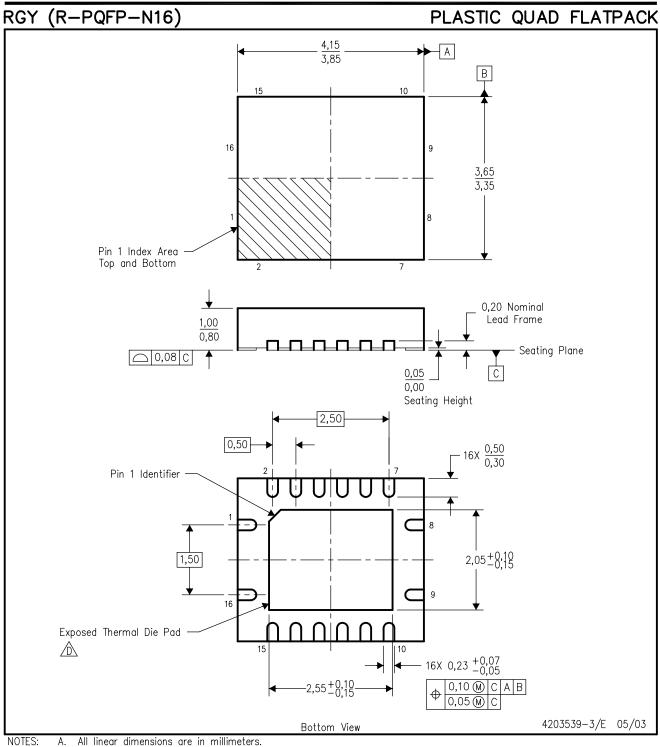
## Figure 9. Test Circuit for Off Isolation (OIRR)

Off-isolation is measured at the output of the OFF channel. For example, when  $V_{IN} = V_{CC}$ ,  $V_{EN} = 0$ , and  $D_A$  is the input, the output is measured at S1<sub>A</sub>. All unused analog input (D) ports are left open, and output (S) ports are connected to GND through 50- $\Omega$  pulldown resistors.

## HP8753ES setup

Average = 4 RBW = 3 kHz  $V_{BIAS}$  = 0.35 V ST = 2 s P1 = 0 dBM





Α.

Β. This drawing is subject to change without notice.

C. QFN (Quad Flatpack No-Lead) package configuration.

 ${
m ar{D}}$  The package thermal performance may be enhanced by bonding the thermal die pad to an external thermal plane. This pad is electrically and thermally connected to the backside of the die and possibly selected ground leads.

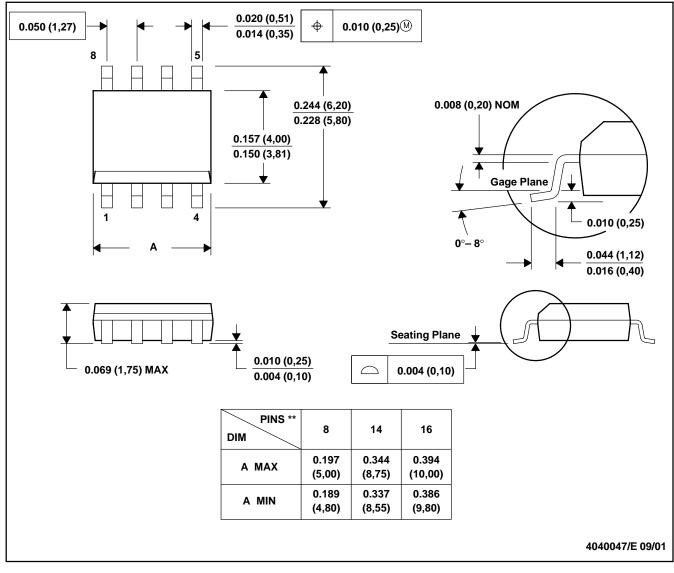
E. Package complies to JEDEC MO-241 variation BB.



MSOI002B - JANUARY 1995 - REVISED SEPTEMBER 2001

#### PLASTIC SMALL-OUTLINE PACKAGE

## D (R-PDSO-G\*\*) 8 PINS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

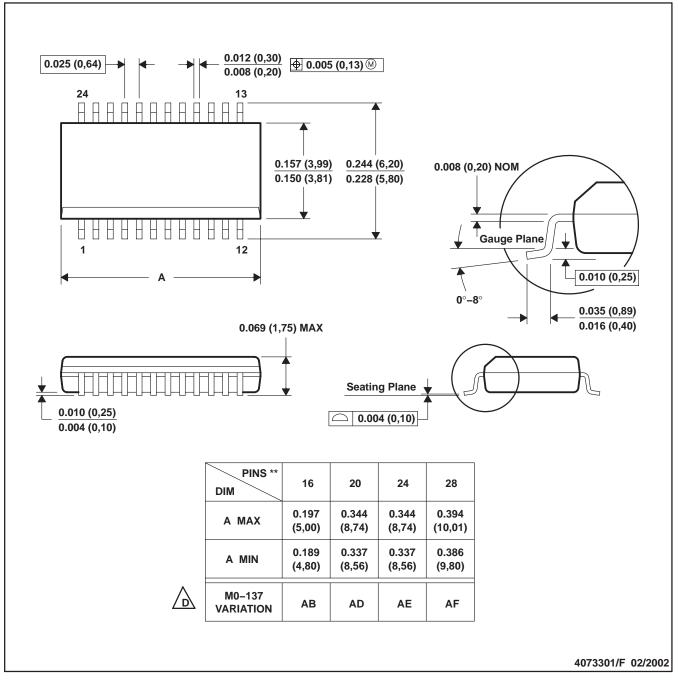
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012



MSOI004E JANUARY 1995 - REVISED MAY 2002



PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-137.



MTSS001C - JANUARY 1995 - REVISED FEBRUARY 1999

# PW (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
- D. Falls within JEDEC MO-153



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